



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Frederick J. Kiko

App. No. : 10/627,942

Filed : July 25, 2003

For : **HIGH DENSITY ELECTRONICS
ASSEMBLY AND METHOD**

Examiner : Dinh, Tuan T.

Group Art Unit: 2841



27299

PATENT TRADEMARK OFFICE

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

October 31, 2005

(Date)

Robert F. Gazdzinski, Reg. No. 39,990

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**AMENDMENT AND RESPONSE
TO RESTRICTION REQUIREMENT**

10 Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

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Dear Sir:

In response to the Office Action dated October 3, 2005 ("Office Action"), the following is provided:

11/03/2005 JBALINAN 00000053 501423 10627942

01 FC:1202 50.00 DA
02 FC:1806 180.00 DA

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RESTRICTION ELECTION

5 By this paper, Applicant elects without traverse the invention of Group I (Claims 1-28, and 31) drawn to an electronics assembly, an electronic insert element, a backplane element, a backplane assembly, a high density electronics assembly housing structure, and a user-configurable electronics assembly, classified in class 361, subclass 796, per Page 2 of the Office Action. Applicant herein cancels the remaining non-elected claims without prejudice. Applicant submits that all claims presented herein for examination (including new claims) read on the elected Group I invention.